

### **Investor Contacts:**

## **NEWS RELEASE**

## **SMIC Reports 2010 First Quarter Results**

All currency figures stated in this report are in US Dollars unless stated otherwise. The financial statement amounts in this report are determined in accordance with US GAAP.

**Shanghai, China – May 11, 2010.** Semiconductor Manufacturing International Corporation (NYSE: SMI; SEHK: 981) ("SMIC" or the "Company"), one of the leading semiconductor foundries in the world, today announced its consolidated results of operations for the three months ended March 31, 2010.

## First Quarter 2010 Highlights:

- Revenue exceeded our original guidance and was up by 5.6% to \$351.7 million in 1Q10 from \$333.1 million in 4Q09 and up by 140.1% compared to 1Q09.
- Gross margins improved to 14.6% in 1Q10 compared to 7.6% in 4Q09 primarily due to an increase in wafer shipments and higher ASP.
- Net cash flow from operations has increased to \$153.1 million in 1Q10 from \$89.3 million in 4Q09.
- Loss attributable to holders of ordinary shares narrowed to US\$181.9 million in 1Q10, compared to loss of US\$617.7 million in 4Q09.
- Fully diluted EPS was (\$0.41) per ADS.

### Second Quarter 2010 Guidance:

The following statements are forward looking statements which are based on current expectation and which involve risks and uncertainties, some of which are set forth under "Safe Harbor Statements" below.

- Revenue is expected to range from 3% to 5% increase.
- Operating expenses excluding foreign exchange differences are expected to range from \$80 million to \$84 million.
- Capital expenditures expected to range from \$150 miom ex m



## Conference Call / Webcast Announcement

Date: Wednesday, May 12, 2010 Time: 8:30 a.m. Shanghai time Dial-in numbers and pass code:

> US 1-617-614-3672 (Pass code: SMIC) HK 852-3002-1672 (Pass code: SMIC)

A live webcast of the 2010 first quarter announcement will be available at http://www.smics.com under the "Investor Relations" section, or at

URL: http://phx.corporate-ir.net/playerlink.zhtml?c=176474&s=wm&e=3029260.

An archived version of the webcast, along with an electronic copy of this news release will be available on the SMIC website for a period of 12 months following the webcast.

## **About SMIC**

Semiconductor Manufacturing International Corporation ("SMIC"; NYSE: SMI; SEHK: 981) is one of the leading semiconductor foundries in the world and the largest and most advanced foundry in Mainland China, providing integrated circuit (IC) foundry and technology services at 0.35-micron to 45-nanometer. Headquartered in Shanghai, China, SMIC has a 300mm wafer fabrication facility (fab) and three 200mm wafer fabs in its Shanghai mega-fab, two 300mm wafer fabs in its Beijing mega-fab, a 200mm wafer fab in Tianjin, a 200mm fab under construction in Shenzhen, and an in-house assembly and testing facility in Chengdu. SMIC also has customer service and marketing offices in the U.S., Europe, and Japan, and a representative office in Hong Kong. In addition, SMIC manages and operates a 200mm wafer fab in Chengdu owned by Cension Semiconductor Manufacturing Corporation, and a 300mm wafer fab in Wuhan owned by Wuhan Xinxin Semiconductor Manufacturing Corporation.

For more information, please visit www.smics.com

## Safe Harbor Statements

(Under the Private Securities Litigation Reform Act of 1995)

This press release contains, in addition to historical information, "forward-looking statements" within the meaning of the "safe harbor" provisions of the U.S. Private Securities Litigation Reform Act of 1995. These forward-looking statements, including statements concerning, the Company continues to see uptrend in the second quarter and remain cautiously optimistic about the second half of 2010; the Company's goal of sustainable profitability and statements under "Second Quarter 2010 Guidance" are based on SMIC's current assumptions, expectations and projections about future events. SMIC uses words like "believe," "anticipate," "intend," "estimate," "expect," "project," "confident" and similar expressions to identify forward-looking statements, although not all forward-looking statements contain these words. These forward-looking statements are necessarily estimates reflecting the best iudgment of SMIC's senior management and involve significant risks, both known and unknown. uncertainties and other factors that may cause SMIC's actual performance, financial condition or results of operations to be materially different from those suggested by the forward-looking statements. including among others, risks associated with cyclicality and market conditions in the semiconductor industry, intense competition, timely wafer acceptance by SMIC's customers, timely introduction of new technologies, SMIC's ability to ramp new products into volume, supply and demand for semiconductor foundry services, industry overcapacity, shortages in equipment, components and raw materials, availability of manufacturing capacity, financial stability in end markets, future fluctuations of the share price of SMIC and possible future litigation and claims.

Investors should consider the information contained in SMIC's filings with the U.S. Securities and Exchange Commission (SEC), including its Annual Report on Form 20-F filed with the SEC on June 22, 2009, especially in the "Risk Factors" and "Management's Discussion and Analysis of Financial



Condition and Results of Operations" sections, and such other documents that SMIC may file with the SEC or SEHK from time to time, including on Form 6-K. Other unknown or unpredictable factors also could have material adverse effects on SMIC's future results, performance or achievements. In light of these risks, uncertainties, assumptions and factors, the forward-looking events discussed in this press release may not occur. You are cautioned not to place undue reliance on these forward-looking statements, which speak only as of the date stated, or if no date is stated, as of the date of this press release. Except as may be required by law, SMIC undertakes no obligation and does not intend to update any forward-looking statement, whether as a result of new information, future events or otherwise.

## **Material Litigation**

The Company settled all pending litigation with TSMC on November 9, 2009, including the legal action filed in California for which a verdict was returned by the jury against SMIC on November 4, 2009, with a Settlement Agreement (the "2009 Settlement Agreement") which replaced the 2005 Settlement Agreement. The 2009 Settlement Agreement resolved all pending lawsuits between the parties and the parties have since dismissed all pending litigation between them. The terms of the 2009 Settlement Agreement include the following:

- 1) Entry of judgment and mutual release of all claims that were or could have been brought in the pending lawsuits;
- 2) Termination of SMIC's obligation to make remaining payments under the 2005 Settlement Agreement between the parties (approximately US\$40 million);



## **Summary of First Quarter 2010 Operating Results**

Amounts in US\$ thousands, except for EPS and operating data

	1Q10	4Q09	QoQ	1Q09	YoY
Revenue	351,724	333,090	5.6%	146,519	140.1%
Cost of sales	300,270	307,669	-2.4%	275,900	8.8%
Gross profit (loss)	51,454	25,421	102.4%	(129,381)	-
Operating expenses	79,496	622,244	-87.2%	46,681	70.3%
Loss from operations	(28,042)	(596,823)	-95.3%	(176,062)	-84.1%
Other expenses, net	(155,567)	(29,178)	433.2%	(4,480)	3372.5%
Income tax benefit	2,374	8,735	-72.8%	3,305	-28.2%
Net loss after income taxes	(181,235)	(617,266)	-70.6%	(177,238)	2.3%
Loss from equity investment	(455)	(114)	299.1%	(874)	-47.9%
Net loss	(181,690)	(617,380)	-70.6%	(178,111)	2.0%
Accretion of interest to noncontrolling interest	(259)	(274)	-5.5%	(259)	0.0%
Loss attributable to Semiconductor Manufacturing International Corporation	(181,949)	(617,655)	-70.5%	(178,370)	2.0%
Gross margin	14.6%	7.6%		-88.3%	
Operating margin	-8.0%	-179.2%		-120.2%	
Net loss per ordinary share (basic) <sup>(1)</sup>	(0.01)	(0.03)		(0.01)	
Net loss per ADS (basic)	(0.41)	(1.38)		(0.40)	
Net loss per ordinary share (diluted) <sup>(1)</sup>	(0.01)	(0.03)		(0.01)	
Net loss per ADS (diluted)	(0.41)	(1.38)		(0.40)	
Wafers shipped (in 8" wafers) <sup>(2)</sup>	455,010	436,816	4.2%	168,743	169.6%
Capacity utilization  Note:	92.1%	91.5%		34.9%	

- Revenue increased to \$351.7 million in 1Q10, up 5.6% QoQ from \$333.1 million in 4Q09 due to a 4.2% increase in wafer shipments.
- Cost of sales decreased to \$300.3 million in 1Q10, down 2.4% QoQ from \$307.7 million in 4Q09.
- Gross profit of \$51.5 million in 1Q10, compared to a gross profit of \$25.4 million in 4Q09 and gross loss of \$129.4 million in 1Q09.

<sup>(1)</sup> Based on weighted average ordinary shares of 22,397 million (basic) and 22,397 million (diluted) in 1Q10, 22,370 million (basic) and 22,370 million (diluted) in 4Q09 and 22,344 million (basic) and 22,344 million (diluted) in 1Q09

<sup>(2)</sup> Including copper interconnects



- Gross margins improved to 14.6% in 1Q10 from 7.6% in 4Q09 primarily due to an increase in wafer shipments and higher ASP.
- Total operating expenses decreased to \$79.5 million in 1Q10 from \$622.2 million in 4Q09, a decrease of 87.2% QoQ primarily due to a decrease in G&A related expenses, larger impairment loss of long-lived assets, and litigation settlement expenses associated with 4Q09.
- R&D expenses decreased to \$43.6 million in 1Q10, down 0.5% QoQ from \$43.8 million in 4Q09.
- G&A expenses decreased to \$17.6 million in 1Q10 from \$151.5 million in 4Q09 due to decreased legal expenses and bad debt expenses.
- Selling & marketing expenses decreased to \$6.0 million in 1Q10, down 22.1% QoQ from \$7.8 million in 4Q09.



**Analysis of Revenues** 

Sales Analysis			
By Application	1Q10	4Q09	1Q09
Computer	4.3%	6.2%	4.2%
Communications	51.5%	49.0%	50.9%
Consumer	37.0%	38.3%	32.9%
Others	7.2%	6.5%	12.0%
By Service Type	1Q10	4Q09	1Q09
Logic <sup>(1)</sup>	90.3%	90.2%	85.3%
Memory	2.7%	3.4%	2.8%
Mask Making, testing, others	7.0%	6.4%	11.9%
By Customer Type	1Q10	4Q09	1Q09
Fabless semiconductor companies	66.4%	64.4%	70.9%
Integrated device manufacturers (IDM)	17.0%	17.4%	11.4%
System companies and others	16.6%	18.2%	17.7%
By Geography	1Q10	4Q09	1Q09
North America	58.9%	56.4%	60.4%
China <sup>(2)</sup>	24.4%	21.9%	21.4%
Eurasia <sup>(3)</sup>	16.7%	21.7%	18.2%
Wafer Revenue Analysis			
By Technology (logic, memory & copper interconnect only)	1Q10	4Q09	1Q09
0.09μm and below	20.3%	18.7%	8.2%
$0.13 \mu m$	35.5%	39.5%	30.8%
0.15μm	1.5%	2.7%	0.8%
0.18μm	24.2%	22.9%	31.5%
0.25μm	0.3%	0.3%	0.4%
0.35μm	18.2%	15.9%	28.3%

- (1) Including 0.13µm copper interconnects
  (2) Including Hong Kong
  (3) Excluding China
- - Shipment comprising  $0.09\mu m$  and below made up 20.3% of overall wafer revenue in 1Q10 as compared to 18.7% in 4Q09.



Capacity\*

Fab / (Wafer Size)	1Q10	4Q09
Shanghai Mega Fab (8")	84,000	85,000
Beijing Mega Fab (12")	46,800	42,750
Tianjin Fab (8")	34,300	34,300
Total monthly wafer fabrication capacity	165,100	162,050

Note:

**Shipment and Utilization** 

5p5 5			
8" equivalent wafers	1Q10	4Q09	1Q09
Wafer shipments including copper interconnects	455,010	436,816	168,743
Utilization rate <sup>(1)</sup>	92.1%	91.5%	34.9%

Note:

Wafer shipments increased 4.2% QoQ to 455,010 units of 8-inch equivalent wafers in 1Q10 from 436,816 units of 8-inch equivalent wafers in 4Q09, and up 169.6% YoY from 168,743 8-inch equivalent wafers in 1Q09.

<sup>\*</sup> Wafers per month at the end of the period in 8" equivalent wafers

<sup>(1)</sup> Capacity utilization based on total wafer out divided by estimated capacity



## **Detailed Financial Analysis**

**Gross Profit Analysis** 

Amounts in US\$ thousands	1Q10	4Q09	QoQ	1Q09	YoY
Cost of sales	300,270	307,669	-2.4%	275,900	8.8%
Depreciation	143,919	142,196	1.2%	158,000	-8.9%
Other manufacturing costs	155,119	162,501	-4.5%	111,166	39.5%
Deferred cost amortization	-	1,962	-	5,886	-
Share-based compensation	1,232	1,010	22.0%	848	45.3%
Gross profit (loss)	51,454	25,421	102.4%	(129,381)	-
Gross margin	14.6%	7.6%		-88.3%	

- Cost of sales decreased to \$300.3 million in 1Q10, down 2.4% QoQ from \$307.7 million in 4Q09.
- Gross profit of \$51.5 million in 1Q10, compared to a gross profit of \$25.4 million in 4Q09 and gross loss of \$129.4 million in 1Q09.
- Gross margins improved to 14.6% in 1Q10 from 7.6% in 4Q09 primarily due to an increase in wafer shipments and higher ASP.

Operating Expense Analysis

Amounts in US\$ thousands	1Q10	4Q09	QoQ	1Q09	YoY
Total operating expenses	79,496	622,244	-87.2%	46,681	70.3%
Research and development	43,592	43,806	-0.5%	18,494	135.7%
General and administrative	17,601	151,520	-88.4%	14,928	17.9%
Selling and marketing	6,045	7,760	-22.1%	4,208	43.7%
Amortization of intangible assets	6,886	7,641	-9.9%	9,031	-23.7%
Loss from disposal of properties	233	3,585	-93.5%	20	1065.0%
Impairment loss of long-lived assets	5,138	138,295	-96.3%	-	-
Litigation settlement	-	269,637	-	-	-

- Total operating expenses decreased to \$79.5 million in 1Q10 from \$622.2 million in 4Q09, a
  decrease of 87.2% QoQ primarily due to a decrease in G&A related expenses, larger
  impairment loss of long-lived assets, and litigation settlement expenses associated with 4Q09.
- R&D expenses decreased to \$43.6 million in 1Q10, down 0.5% QoQ from \$43.8 million in 4Q09.
- G&A expenses decreased to \$17.6 million in 1Q10 from \$151.5 million in 4Q09 due to a decrease in legal fees and bad debt expenses.
- Selling & marketing expenses decreased to \$6.0 million in 1Q10, down 22.1% QoQ from \$7.8 million in 4Q09.

Other Income (Expenses)

Amounts in US\$ thousands	1Q10	4Q09	QoQ	1Q09	YoY
Other income (expenses)	(155,567)	(29,178)	433.1%	(4,480)	3372.5%
Interest income	878	886	-0.9%	436	101.2%
Interest expense Change in the fair value of commitment	(7,784)	(2,874)	170.8%	(5,498)	41.6%
to issue shares and warrants	(146,561)	(30,100)	386.9%	-	-
Foreign currency exchange gain (loss)	(3,241)	1,876	-	(357)	807.8%
Other, net	1,141	1,033	10.5%	939	21.5%



- Combined with the foreign exchange difference arising from operating activities, the Company recorded an overall foreign exchange loss of \$1.7 million in 1Q10 as compared to a foreign exchange gain of \$3.1 million in 4Q09.
- Other non-operating expenses in 1Q10 included a change in the fair value of the commitment to grant shares and warrants in connection with the



Capital Structure

Amounts in US\$ thousands	1Q10	4Q09
Cash and cash equivalents	523,208	443,463
Restricted cash	29,286	20,360
Current portion of promissory note	59,163	78,608
Promissory note	83,913	83,325
Short-term borrowings	333,795	286,864
Current portion of long-term debt	204,442	205,784
Long-term debt	515,876	550,653
Total debt	1,054,113	1,043,301
Shareholders' equity	1,618,038	1,796,240
Total debt to equity ratio	65.1%	58.1%

## **Cash Flow**

Amounts in US\$ thousands	1Q10	4Q09
Net cash from operating activities	153,094	89,297
Net cash from investing activities	(64,323)	(37,804)
Net cash from financing activities	(8,762)	(60,937)
Net change in cash	79,745	(9,822)

## **Capex Summary**

• Capital expenditures for 1Q10 were \$64 million.



## **Recent Highlights and Announcements**

- 2009 Annual Report (2010-04-29)
- Circular (1) Notice of AGM (2) Re-Election of Directors (3) Proposed General Mandates to Issue and Repurchase Shares (4) Proposed Special Mandate for Increasing The Limit On The Grant Of Equity Awards under The 2004 Equity Incentive Plan (5) Proposed Amendments To The 2004 Equity Incentive Plan (2010-04-29)
- Notification Letter and Change Request Form (2010-04-29)
- Notice of Annual General Meeting (2010-04-29)
- Notification of Board Meeting (2010-04-28)
- Announcement of 2009 Annual Results (2010-04-26)
- SMIC Issues Updates on First Quarter 2010 Financial Results and 2009 Annual Results (2010-04-19)
- Notification of Approval of the publication of 2009 Annual Results by the Board (2010-04-13)
- Price Sensitive Information SMIC 45LL Technology Has Successfully Completed Process Qualification and SRAM Product Qualification (2010-03-30)
- Grant of Option (2010-02-24)
- GalaxyCore Announces New Milestone: Shipment Of 100K 8" Wafers Using SMIC's CMOS Image Sensor Process (2010-02-12)
- Clarification Announcement (2010-02-09)
- SMIC Reports Results For The Three Months Ended December 31, 2009 (2010-02-09)
- Appointment of Chief Business Officer, Chief Operating Officer and Chief Financial Officer (2010-02-09)
- SMIC And SHHIC In Commercial Production Of 0.162um Embedded EEPROM (2010-02-02)
- Notification of Board Meeting (2010-01-25)

Please visit SMIC's website at http://www.smics.com/website/enVersion/Press\_Center/newsRelease.ftl for further details regarding the recent announcements.



# Semiconductor Manufacturing International Corporation CONSOLIDATED BALANCE SHEET (In US dollars, except share data)

	As of		
	March 31, 2010 (Unaudited)	December 31, 2009 (Unaudited)	
ASSETS	(5	(1 11111)	
Current assets:			
Cash and cash equivalents	523,207,927	443,462,514	
Restricted cash	29,286,422	20,360,185	
Accounts receivable, net of allowances of			
\$96,111,136 and \$96,144,543 at March 31, 2010 and	004.000.070	004 000 545	
December 31, 2009, respectively	204,982,678	204,290,545	
Inventories	194,604,324	193,705,195	
Prepaid expense and other current assets	32,269,099	28,881,867	
Assets held for sale	13,244,958 8,173,216	8,184,462 9,173,216	
Current portion of deferred tax assets  Total current assets	1,005,768,624	8,173,216 <b>907,057,984</b>	
Total current assets	1,003,768,624	907,007,904	
Prepaid land use rights	77,550,315	78,111,788	
Plant and equipment, net	2,129,575,807	2,251,614,217	
Acquired intangible assets, net	177,109,741	182,694,105	
Equity investment	9,392,886	9,848,148	
Other long-term prepayments	214,588	391,741	
Deferred tax assets	98,651,547	94,358,635	
TOTAL ASSETS =	3,498,263,508	3,524,076,618	
LIABILITIES AND STOCKHOLDERS' EQUITY			
Current liabilities:	227 075 007	220 002 004	
Accounts payable	237,075,087	228,882,804	
Accrued expenses and other current liabilities	116,494,349	111,086,991	
Short-term borrowings	333,794,887	286,864,063	
Current portion of promissory notes	59,163,022	78,608,288	
Current portion of long-term debt	204,442,433	205,784,080	
Commitment to issue shares and warrants relating to			
litigation settlement	266,798,990	120,237,773	
Income tax payable	81,310	58,573	
Total current liabilities	1,217,850,078	1,031,522,572	
Long-term liabilities:			
Non-current portion of promissory	22 242 222	00.004.044	
notes	83,912,660	83,324,641	
Long-term debt	515,875,782 4,837,526	550,653,099 4,779,562	
Long-term payables relating to license agreements Other long-term liabilities	21,647,675	21,679,690	
Deferred tax liabilities	1,001,293	1,035,164	
Total long-term liabilities	627,274,936	661,472,156	
	02.,2,000		
Total liabilities	1,845,125,014	1,692,994,728	
Noncontrolling interest	35,100,411	34,841,507	
Stockholders' equity:			
Ordinary shares, \$0.0004 par value, 50,000,000,000 shares authorized, 22,420,895,812 and 22,375,886,604 shares issued and outstanding at March 31, 2010 and December 31, 2009, respectively	8,968,359	8,950,355	
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# Semiconductor Manufacturing International Corporation CONSOLIDATED BALANCE SHEET (In US dollars, except share data)

Additional paid-in capital	3,503,714,048	3,499,723,153
Accumulated other comprehensive loss	(648,316)	(386,163)
Accumulated deficit	(1,893,996,008)	(1,712,046,962)
Total stockholders' equity	1,618,038,083	1,796,240,383
TOTAL LIABILITIES, NONCONTROLLING INTEREST	0.400.000.500	0.504.070.040
AND STOCKHOLDERS' EQUITY	3,498,263,508	3,524,076,618

Semiconductor Manufacturing International Corporation



## Semiconductor Manufacturing International Corporation CONSOLIDATED STATEMENT OF CASH FLOWS (In US dollars)

	For the three months ended		
	March 31, 2010 (Unaudited)	December 31, 2009 (Unaudited)	
Operating activities			
Net loss	(181,690,142)	(617,380,324)	
Adjustments to reconcile net loss to net cash provided by			
operating activities:			
Deferred tax	(4,326,783)	(8,786,497)	
Loss from sale of equipment and other fixed assets	233,053	3,585,371	
Depreciation and amortization	164,246,614	173,502,837	
Amortization of acquired intangible assets	6,885,746	7,640,689	
Share-based compensation	3,583,507	2,620,497	
Non-cash interest expense on promissory note and	, ,	, ,	
long-term			
payable relating to license agreements	1,129,497	1,068,177	
Loss from equity investment	455,261	114,272	
Impairment loss of long-lived assets	5,137,925	138,294,783	
Litigation settlement (noncash portion)	-	239,637,431	
Change in the fair value of commitment to issue shares and warrants	146,561,217	30,100,793	
Allowance for doubtful accounts	(33,407)	110,755,616	
Changes in operating assets and liabilities:	(55,407)	110,755,010	
Accounts receivable, net	(658,725)	(22,556,104)	
Inventories	(899,129)	(6,865,736)	
Prepaid expense and other current assets	(3,210,079)	29,771,367	
Accounts payable	8,714,410	4,697,376	
Accrued expenses and other current liabilities	6,973,898	(8,654,694)	
Income tax payable	22,737	(3,928,422)	
Other long term liabilities	(32,015)	15,679,690	
Net cash provided by operating activities	153,093,585	89,297,122	
Investing activities:			
Purchase of plant and equipment and land use right Proceeds from government subsidy to purchase plant	(72,950,296)	(49,052,074)	
and equipment	23,884,935	13,450,232	
Proceeds from sale of equipment	5,045,012	1,427,816	
Proceeds received from sale of assets held for sale	1,286,854	737,986	
Purchases of acquired intangible assets	(12,663,539)	(10,189,252)	
Purchase of short-term investments	(2,668,692)	(6,802,116)	
Sale of short-term investments	2,668,692	12,912,347	
Changes in restricted cash	(8,926,238)	(289,409)	
Net cash used in investing activities	(64,323,272)	(37,804,470)	
Financing activities:			
Decreeds from about to see he see	474 004 440	17F 711 000	
Proceeds from short-term borrowing	171,264,418	175,741,829	
Repayment of short-term borrowings	(124,333,593)	(170,120,268)	
Proceeds from long-term debt	10,000,000	49,195,984	
Repayment of long-term debt	(46,118,964)	(115,850,696)	



# Semiconductor Manufacturing International Corporation CONSOLIDATED STATEMENT OF CASH FLOWS (In US dollars)

Net cash used in financing activities	(8,762,747)	(60,937,139)
Troccac nom exercise of employee eleak epitens	120,002	00,012
Proceeds from exercise of employee stock options	425.392	96.012
Repayment of promissory notes	(20,000,000)	-